

MOTIVATION



Bees are struggling to survive with each passing day



The world needs environmental support of bees



Apiarists are facing extreme colony loss



Most colony loss issues could be prevented with more knowledge and data



The apiary industry is not technologically up to date



Streamlining an industry such as this benefits everyone



GOALS AND OBJECTIVES

- Creating a data gathering system that is capable of transmitting data over a long-range communication network.
- Create a board that mainly monitors temperature, humidity, pressure, GPS location, and light sensitivity.
- Secondary additions can be made, such as adding rainfall measurement systems, as well as a vibration sensor.
- RFID tags can also be used to identify each individual hive on site.

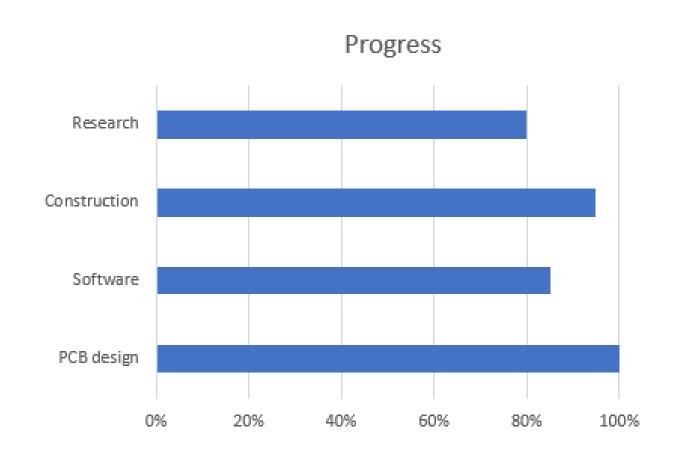
ENGINEERING SPECIFICATIONS

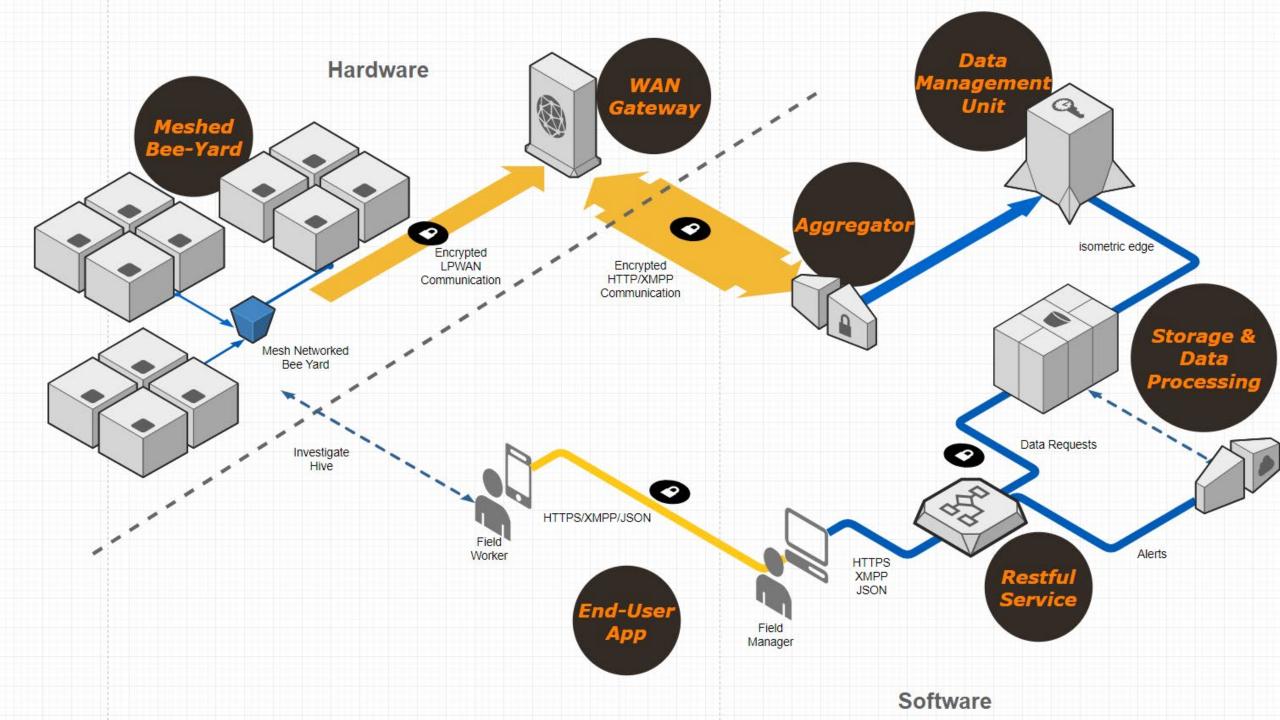
Specification	Description			
Range of Communications	Reach of 10 mi. at Sub-1 GHz bands. Inversely correlated to response time and cost.			
Product Dimension	Able to fit the space between hives.			
Power Consumption	Supply only the minimal amount of power through solar panels for efficiency and cost.			
Weather Resistance	Exposed to the elements. The product should last and hold its own.			
Easy to Assemble/Install	Easy to set by anyone with zero experience.			

MEMBERSHIP RESPONSIBILITIES

	PCB Design	Software	Construction	Research
Primary	Tariq Ausaf	Yannick Roberts	Katelyn Winters	Giovanny Reyes
Secondary	Katelyn Winters	Tariq Ausaf	Giovanny Reyes	Yannick Roberts

PROGRESS





HARDWARE

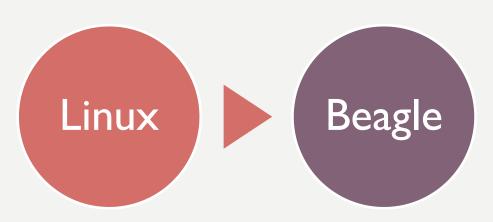
HARDWARE ORGANIZATION

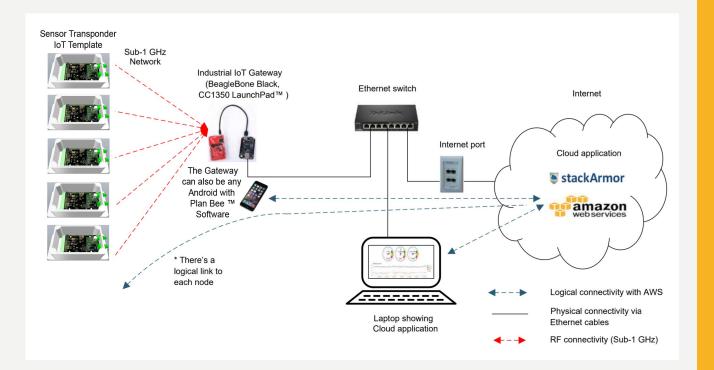
Sensor Transponder

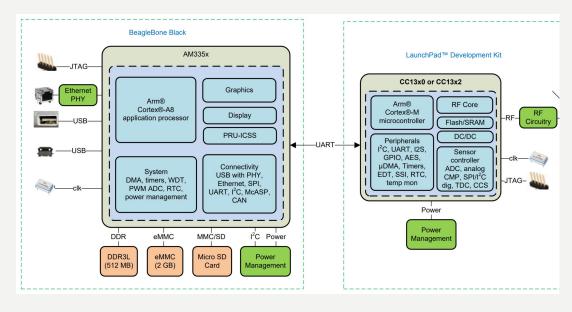
- Long-range communication (10m+) RF Communication Capability (968 MHz)
- Bluetooth 4.0 Capability (2.4 GHz) latches via Zigbee onto Gateway
- GPS Real-time tracking
- Onboard Sensors for General Spatial Monitoring
- Attachable Sensors Interface

GATEWAY ILLUSTRATION

- Maximum of I I 2 per Sensors
 Transponder (SPI / I2C
 Limitations) artificially limited
 at 30
- Maximum of 60 Sensors
 Transponders attached to each
 Gateway









THIS ISN'T UCF ANYMORE...

TI CC1352R WMCU – WHY?

Three Processors embedded at different levels:

- ARM Cortex M4F Processor
- RF Core Processor
 - ARM Cortex M0 Embedded Processor

Supports several interfacing protocols and sensors:

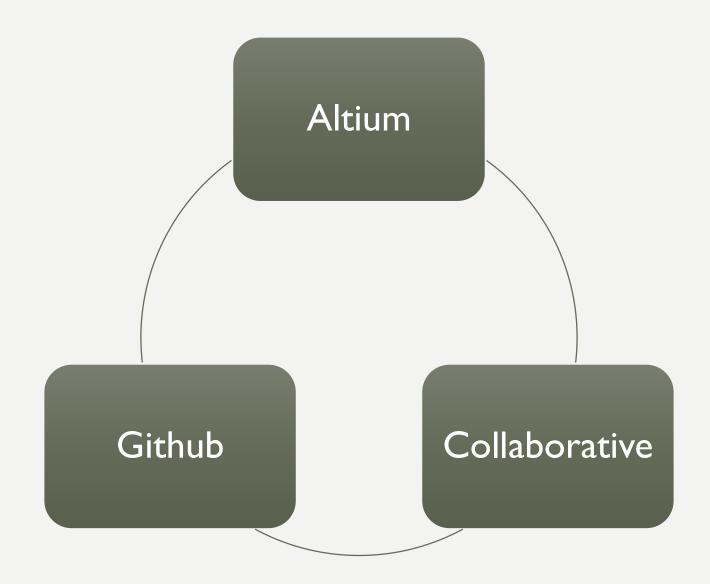
- 2X UART
- I2C and SPI
- 28 additional GPIO (Analog Or Digital)

High-Power
WMCU supporting
both Long-Range
and Short-Range
Communications:

- BLE 4.0 low-energy
- Zigbee
- Thread
- LPWAN
- 10+ miles possible at 14 dBi (antenna gain)

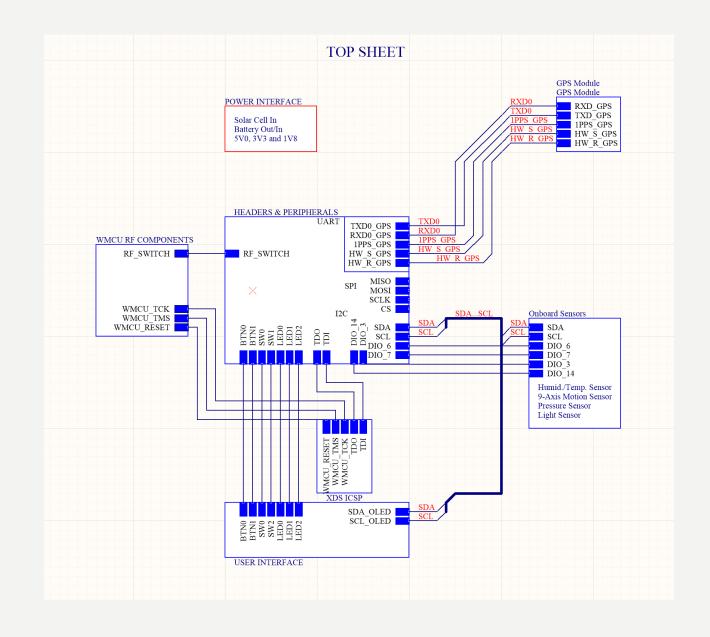
SENSOR TRANSPONDER

HARDWARE DEVELOPMENT



SCHEMATIC OVERVIEW

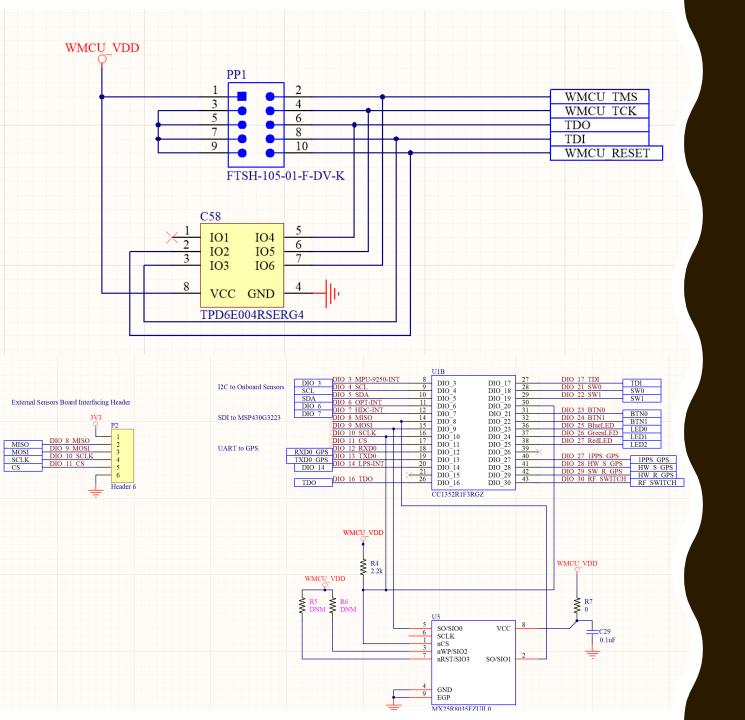
- WMCU RF Components acts like the "brain"
- Headers & Peripherals connect everything together like the "heart"
- XDS is like the "parent"
- UX, GPS and Onboard Sensors like the "eyes and ears"



WMCU_VDD VDDS VDDS3 TAG TCKC RESET_N VDDR 2 4 GHZ RF P PORT1 2 4 GHZ RF N SUB-1_GHZ_RF_F SUB-1 GHZ RF CX2520DB32000D0GEJZ1 SUB-1 GHZ RF P PORT2 RX TX

WIRELESS MCU + RF COMPONENTS

- BLM18HE GHz Noise Suppression Chip Ferrite Bead + Filtering Capacitors for power
- CC1352R1 is the workhorse AMR-based
 MCU + High-Power Wireless Transmission
- 32 kHz (aux timing) and 48 MHz XTALs (MCU CLK)
- PE4259 solid-state RF Switch
- 2.4 GHz Duck Antenna
- Balun "merges" and "splits" differential signal
- Impedance matching for maximum power transfer, minimizing data loss / noise
 - 50 Ohm everywhere...



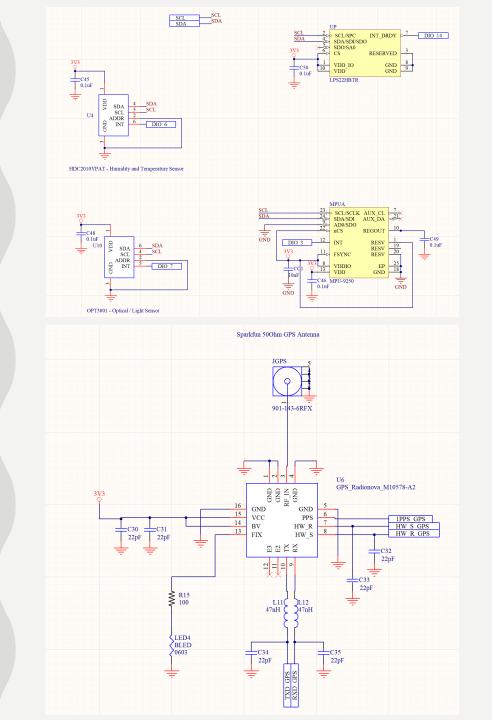
HEADERS & PERIPHERALS + PROGRAMMING INTERFACE

- "Heart" of our Sensors Transponder
- XDS X-Window Direct Save Protocol

 the programming interface we're using to flash the WMCU
- Headers & Peripherals interfaces all onboard and external devices
 - I2C to communicate with onboard sensors
 - UART to communicate with GPS chip
 - SPI to communicate with external sensors interface (MSP432-G)
 - Management of the User Interface (UX)

GPS MODULE + ONBOARD SENSORS

- GPS Similar to WMCU
 - Communicates at 1.582 GHz
 - 50 Ohm everywhere in communication routing lines
 - Frontend + Backend (entire ARM 3 processor)
 - IPPS more precise than CC1352 used to calibrate
 - NMEA GPS data output through UART precise clock local time, location data…
- Humidity and Temperature
- Light Sensor (light level)
- Pressure Sensor
- 9-Axis Motion Sensor (IMU)



ONBOARD SENSORS

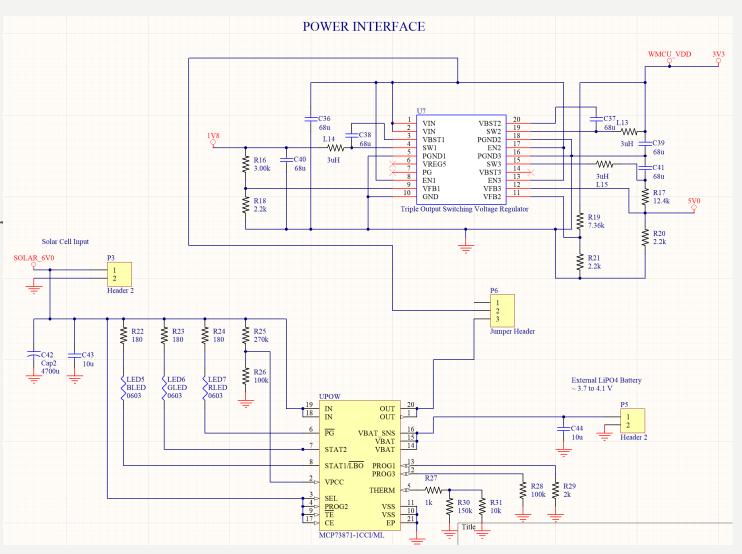
Sensor	Sensor Type	Price	Protocol	Operating Voltage	Temperature Range
MPU 9250	3-Axis Gyroscope, Acelerometer	\$9.32/chip	I^2C and SPI	2.4V to 3.6V	-40°C to 85°C
LPS22HBTR	Pressure Sensor	\$3.28/chip	I^2C and SPI	1.7V to 3.6V	-40°C to 85°C
OPT3001	Ambient Light Sensor	\$3.35/chip	I^2C	1.6 v to 3.6 V	-40°C to 85°C
HDC2010	Humidity and Moisture Sensor	\$3.35/chip	I^2C	1.62 V to 3.6 V	-40°C to 85°C

ANTENNA ALTELIX AU09G6-NF

- Broad Omnidirectional Coverage
- Industrial Grade Construction
- Durable Fiberglass
- All Weather Outdoor Operation

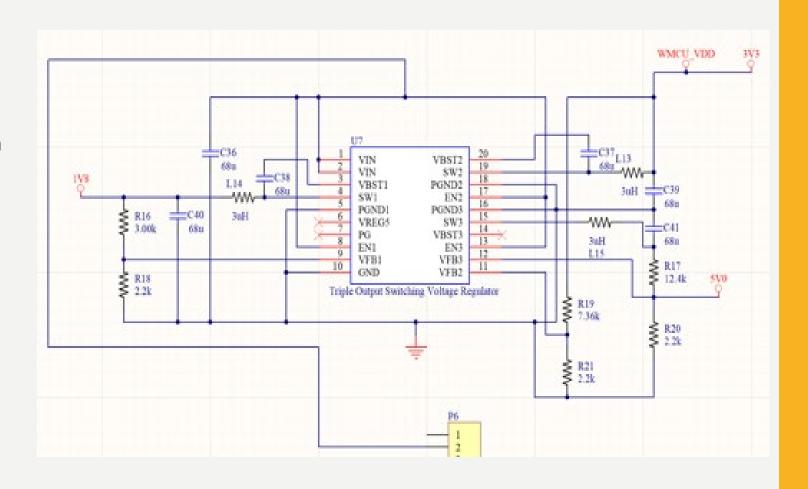
POWER

- Header P3 for 6V Solar Panel Input
- Solar LiPo Charger
 - Routes power from best
 power source available –
 always going to pull from solar
 before the battery
- Header P5 for external LiPo Battery
- Jumper Header to turn power on/off



TPS6580 VOLTAGE REGULATOR

- Switching Voltage Regulator
 - Only Step-down needed
 - 30% or more efficient than comparable linear regulator w/ lower heat generation.
 - 3V3 for most everything
 - IV8 and 5V0 are also available
 - No expensive DC/DC
 - Increased noise



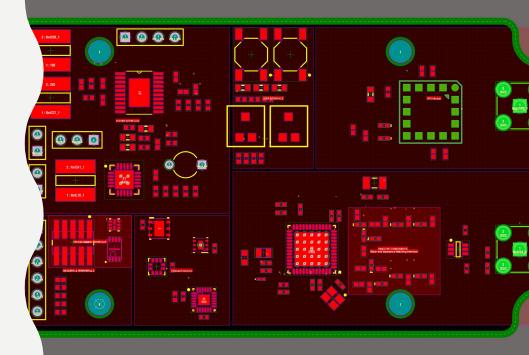
BATTERY

- Lithium polymer battery (LiPo).
- Four times the energy of density of nickel batteries.
- Higher current first for charge.
- More malleable and higher specific energy than regular Li Ion.
- Can be more expensive per volume.

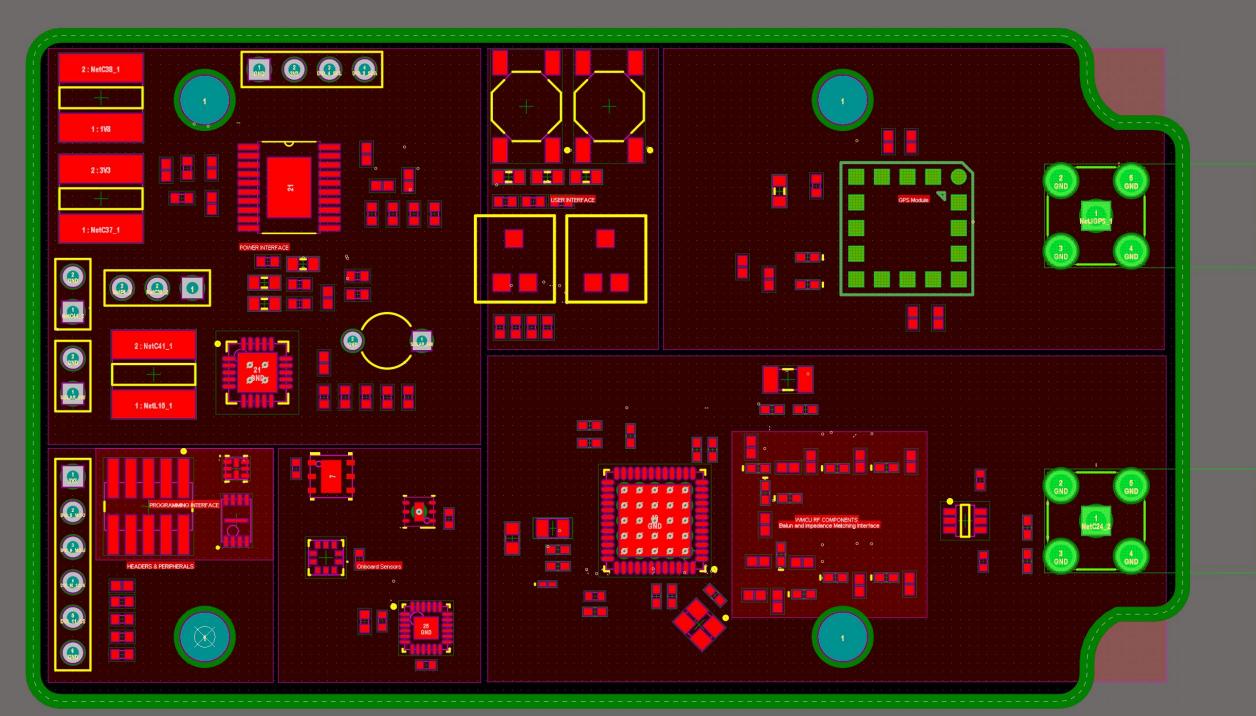


PCB LAYOUT

- GPS on the top-right, about 20 mm away from CC1352R1 below it — Balun and Imped. Match embedded
 - Routing to-and-from RF components is 12 mils thick Copper (50 Ohm trace Impedance, Max Power)
- Normal routing is 7 mils thick throughout the board
- User Interface Top-Center
- Onboard Sensors Bottom-Center
- Headers and Peripherals + XDS Debugging + Power all on far left (bottom-to-top)
 - Minimum 50 mm away from RF components
- 4 layer board
 - RF Component Routing (GPS and CC1352)
 - 15 mil thick dielectric
 - GND Plane
 - 50 mil thick dielectric between ground and power plane
 - Power Plane (vias from power components)
 - 15 mil thick dielectric
 - Routing for everything else
- Board is ready to manufacture!







PCB MANUFACTURING PLAN

- We are getting the PCB manufactured at
 - Advanced PCB* ☺
 - JLCPCB
- Discounted PCBs for students working on SD
- We have purchased a Solder Dispenser and PCB Oven (Infrared IC Heater) for soldering
 - We have a PCB oven at UCF, but unusable
 - Soldering Gun + Solder Flux for any touchups
- Placement we will have to do ourselves
 - 138 components in total on the PCB
 - prohibitively expensive to get this done for a prototype





SOFTWARE

Transponder Firmware

Samples Sensor Data

Stores Sensor Data

Transmits Data to Gateway

Manage Device Parameters

SOFTWARE ORGANIZATION

Additional Resources Utilizes:

Texas Instruments RTOS

Language:

Assembly, C, C++

Gateway Firmware

- Stores Data to local Database
- Transmits Data to an online server
 - Manages Transponder Devices
 - Transmits Data to local user.

SOFTWARE ORGANIZATION

Additional Resources Utilizes:

Linux

SQLite

TI's 15-4 network Stack

XMPP, HTTPS

Language:

C, C++, Python(Automate)

Web Service

- Authenticates and Communicate with Gateway Device
- Utilizes Amazon DynamoDB instance for storage.
- Provides secure RESTful services using Amazon's AWS.

SOFTWARE ORGANIZATION

Additional Resources Utilizes:

Amazon AWS

Amazon IOT core

Amazon App Serv

Amazon DynamoDB

Bootstrap

XMPP/MQTT/HTTP

Language:

Golang, Json, JavaScript,

User Application

- Forwards Recorded data to end users.
- Keeps track of connected devices.
- Divides data into specific categories (yards) based on gateway.

SOFTWARE ORGANIZATION

Additional Resources Utilizes:

Android

SQLite

Language:

Java

XML

GoLang

Python

TRANSPONDER FIRMWARE

Connectivity
Wi-Fi,
Bluetooth®Smart,
ZigBee®,
Cellular (via PPP),
TCP/IP

Optional
Other
Middleware
USB, File Sytems

TI-RTOS

User Application Tasks

APIs

Power Manager

Real-time Kernel

Drivers

TI Devices

TI-RTOS

Multi-Tasks OS

Task Preemption

Hardware Interrupts

Software Interrupts

Task Preemption

Concurrency Control

FIRMWARE ORGANIZATION

The 3 D's

Data Sampler





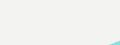




Data Aggregator











Temperature

Gyroscope

Accelerometer

Compass

Ambient Light

Humidity

Pressure

Processing

Timestamp

Identifier

Storage

Maintain

Connects

Data Dispatcher

Encrypts

Transmits

Validates

Configures

System Director

Delegates

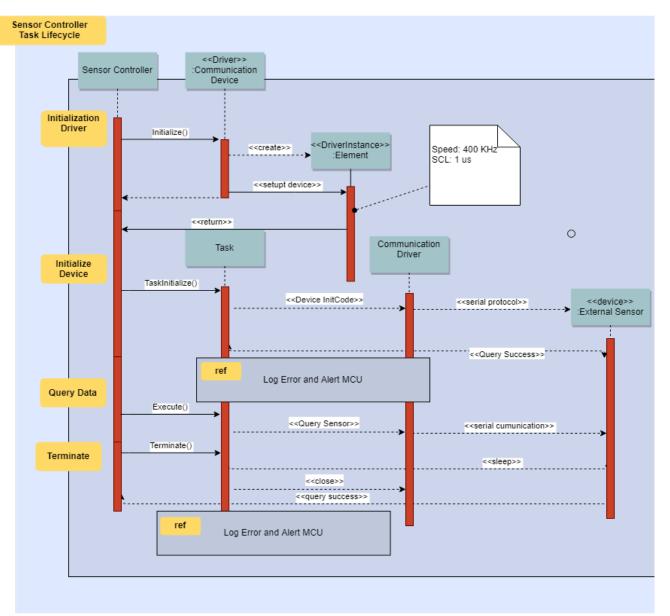
Authenticates

Synchronizes

Alerts

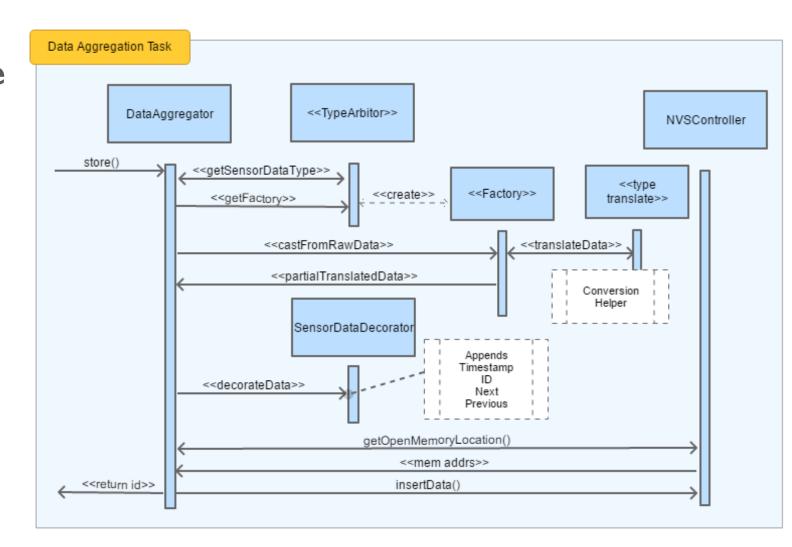
DATA SAMPLER SEQUENCING DIAGRAM

- Executed using the on-bard lowpowered ARM thumb processor, SCU.
- Triggered periodically using the onboard Real-Time-Clock.
- Utilizes standard I2C messaging protocol.
- Pushes data to a shared buffer and triggers a hardware interrupt for main processing unit.



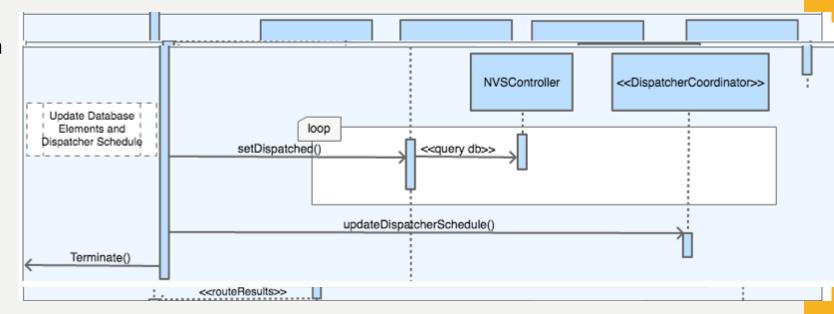
Data Aggregation Sequence Diagram

- Executed on main processor.
- Triggered from hardware interrupt.
- Stores Data to Non-Volatile memory.
- Thread Safe (Semaphores).
- Blocking.



Data Dispatcher
 Sequence Diagram

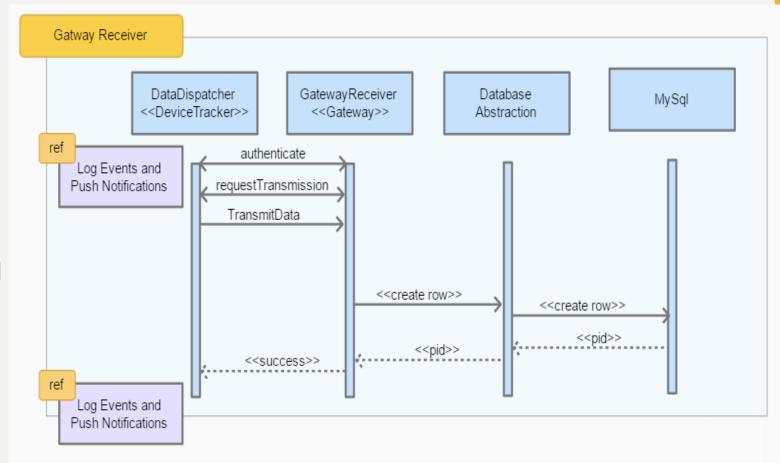
- Periodically Executed on main processor using RTC.
- Transmits data to gateway.
- Thread Safe (Semaphores).



GATEWAY FIRMWARE

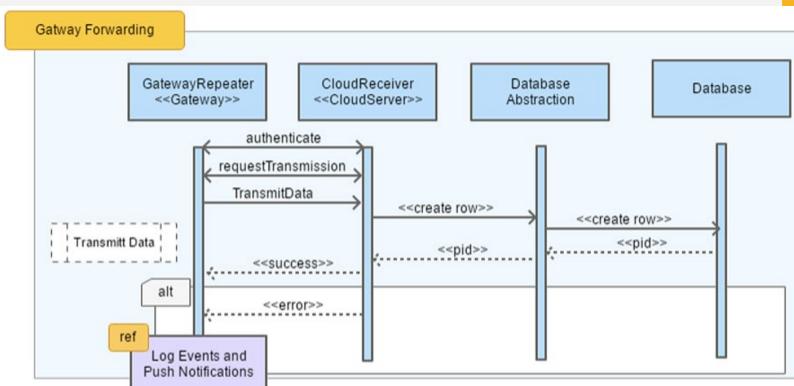
Gateway Receiver Sequence Diagram

- Authenticates transponder device using 256-bit AES encryption key.
- Private key stored on encrypted portion of device.
- Provides primitive network addressing for transponder devices.
- Stores data to local SQLite database.

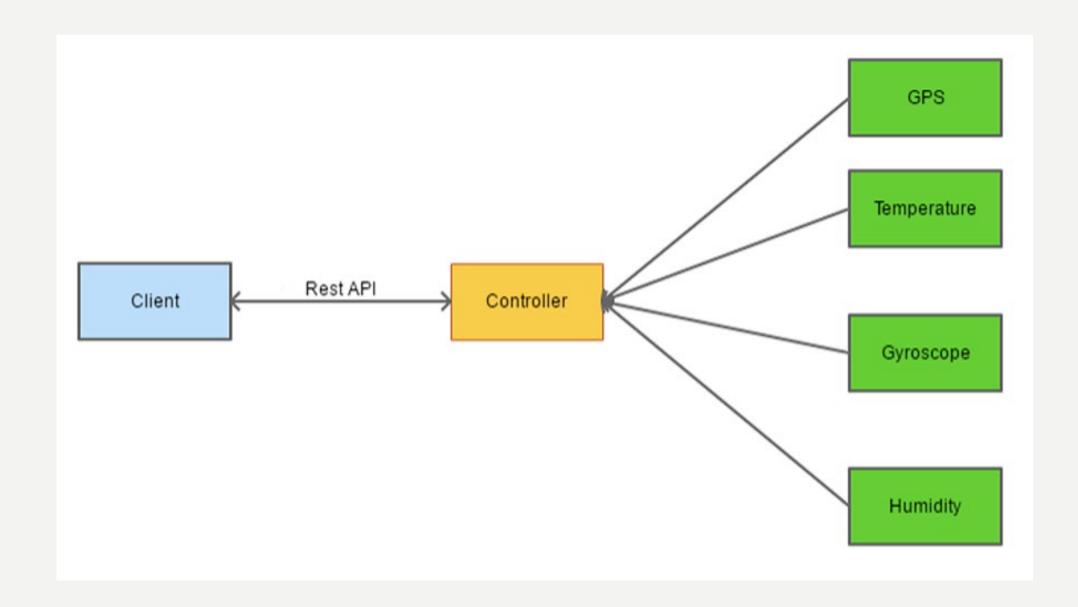


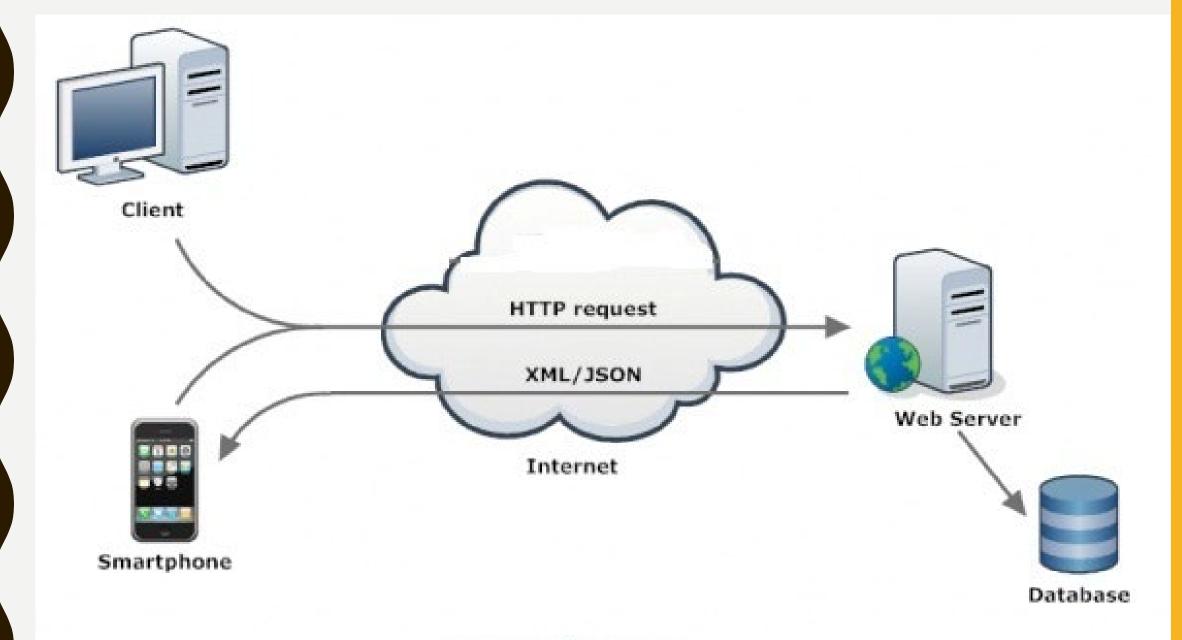
Gateway Forwarding Sequence Diagram

- Authenticates with web service or a nearby mobile device.
- Pushes data using GCM/XMPP protocol.



WEB SERVICE

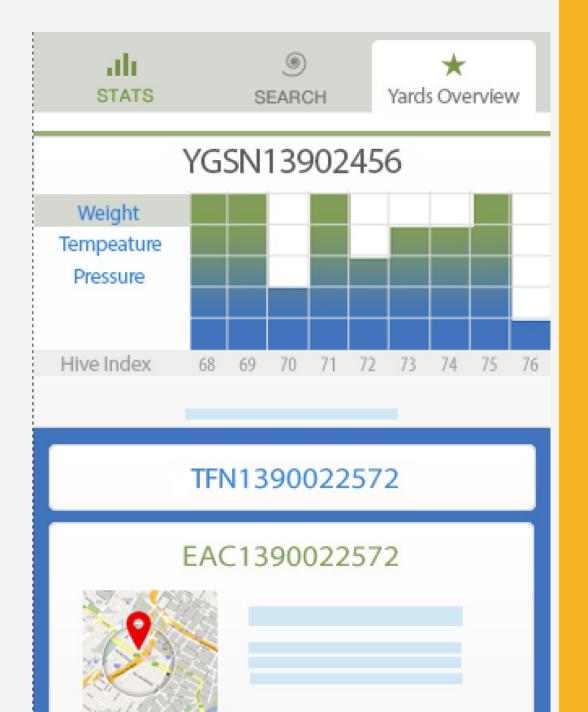


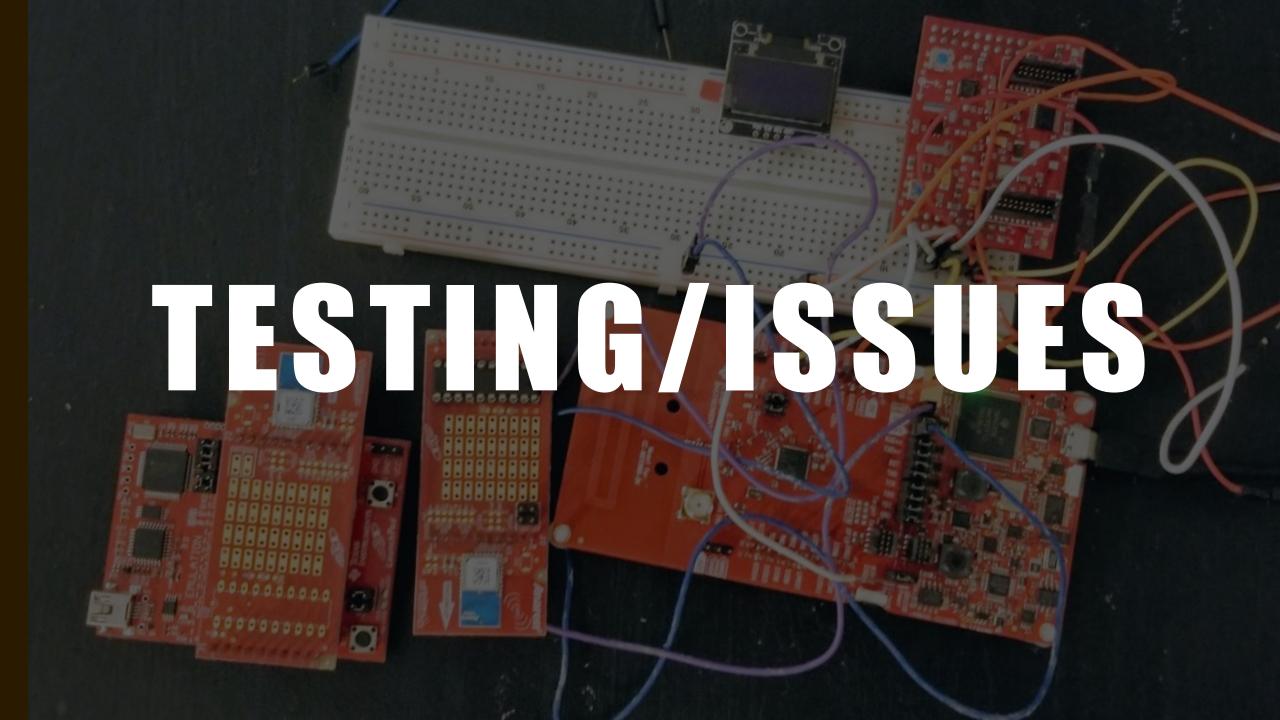


Rest WebService

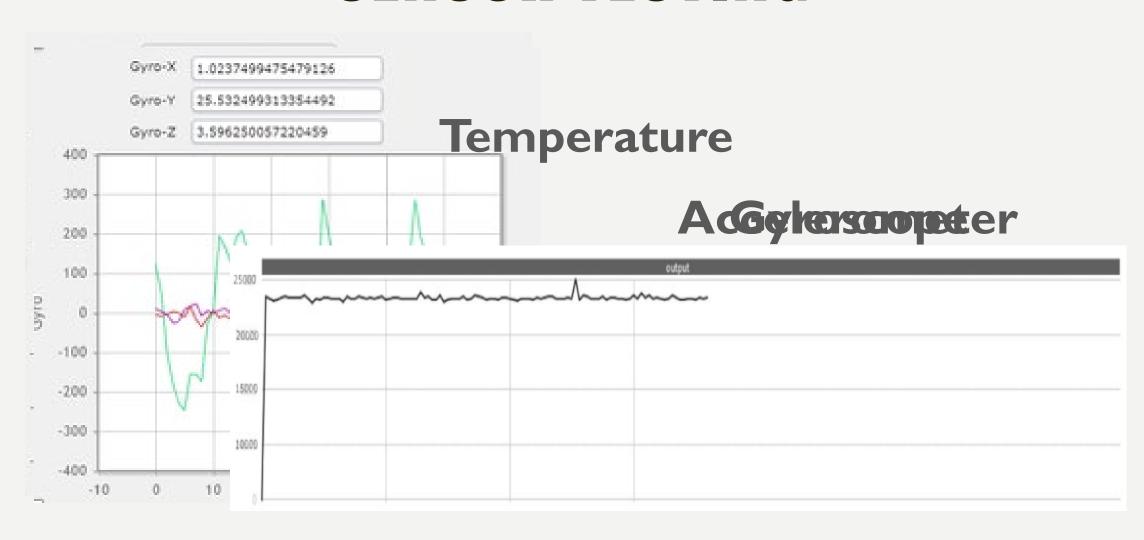
USER APPLICATION

- Read data from gateway and synchronizes with cloud.
- Presents data in an intuitive fashion.



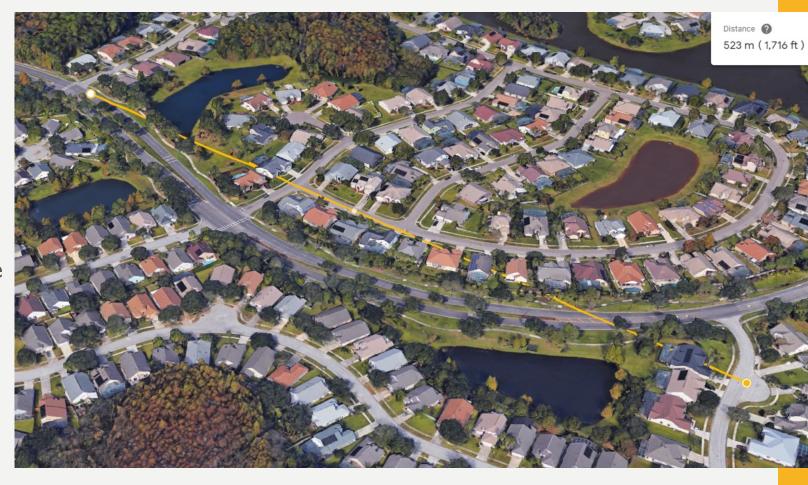


SENSOR TESTING



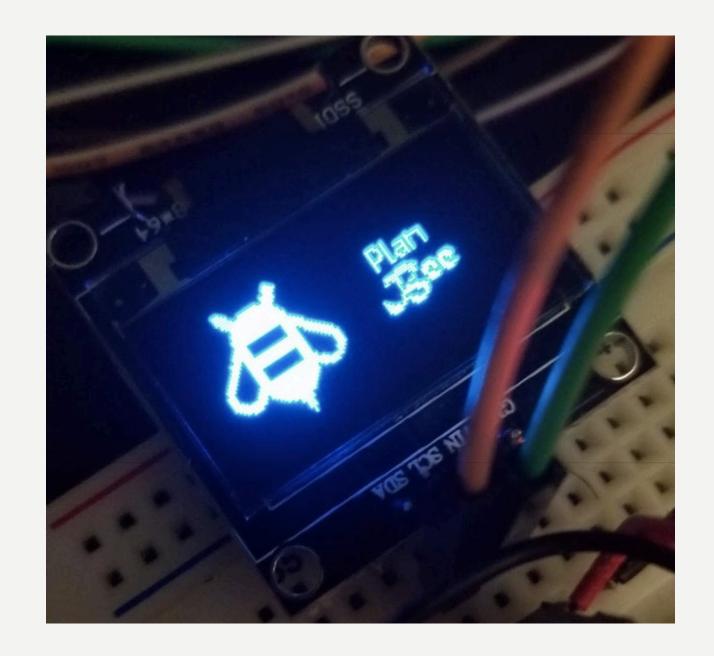
WIRELESS COMMUNICATION TESTING

- Transmit the string "Hello UCF" across sub I-GHz connection.
- We were able to communicate across approximately 500 meters.
- We're expecting to achieve data transfer rates of approximately 100 bytes per second.
- Hives are expected to transmit, on average, 80 bytes per hour.



FURTHER TESTING

- Driver for display has been developed and working. It is able to output texts and binary images.
- Busses are debugged for accuracy using an oscilloscope and logic analyzer.



SOFTWARE UNIT TESTING

- The firmware code is currently being unit tested using Google Testing suite.
- Attempting a test driven development routine where unit tests are written prior to application code.

BUDGET

INITIALLY PROJECTED BUDGET

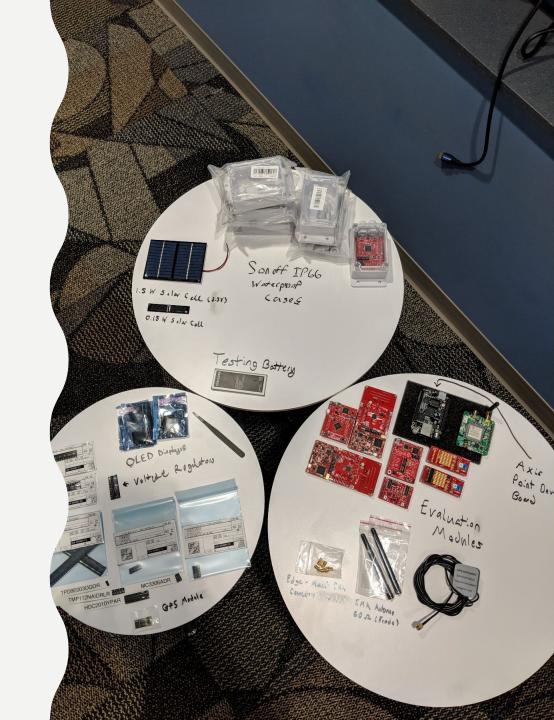
We knew we would run into unexpected costs, and we have. Luckily, we planned for all of this:

- Power Components
- Hardware Prototyping
- Hardware Manufacturing / Fabrication Processes inhouse
- Software Setup and Application Hosting
- Miscellaneous Costs...

Туре	Item/Description	Supplier	Part No.	Unit(s)	Projected	Projected
					EPU (\$) *	Exp. (\$) *
Power	Solar Cells (6.2 W)	Adafruit	1525	3	75.00	225.00
	High Efficiency Synchronous Switch Mode Charger	TI	BQ24650	3	20.00	60.00
	LiFePO ₄ Batteries (1000 mAh)	Westingho use	N/A	3	25.00	75.00
	Solar Panel Mount	Renology	N/A	2	15.00	30.00
	** Miscellaneous Solar Costs					150.00
Hardware Prototyping	Microcontroller including RF Comms Chip	TI	MCU: MSP- EXP430G2 Comm Chip:	2	120.00	240.00
	C IV: (MCD420 MCL)	T1	CCI300x RF	2	35.00	70.00
	Sensors Kit for MSP430 MCUs	TI N/A	Multiple N/A	100	35.00 0.55	70.00 55.00
	Single-Strand 22 Ga. Copper Wire for ICs	IN/A	IN/A	feet	0.55	33.00
ardwa	Varied Basic Electronic Components Kit (Rs, Caps, MOS, Diodes, Op Amps, etc.)	N/A	N/A	4	15.00	60.00
I	**Miscellaneous Hardware Prototyping Costs					200.00
Hardware Fabrication	PCB Fabrication Stage I	Altium	N/A	2	30.00	60.00
	PCB Fabrication Stage 2	Altium	N/A	2	30.00	60.00
	RF Comm. Chips	TI	CC1352R	4	25.00	100.00
	MCU Chips	TI	MSP432	4	12.00	48.00
Ha Fat	**Sensors Costs & Miscellaneous Hardware Fabrication Costs					200.00
Software Setup	Amazon AWS Server	N/A	N/A	1	0.00	0.00
	IBM Watson Al Usage	N/A	N/A	1	0.00	0.00
	Application (Dashboard) Development	N/A	N/A	1	0.00	0.00
	** Software Hosting & Miscellaneous Development Costs					375.00
Miscellaneo us	Final PCB Packaging	N/A	N/A	2	20.00	40.00
	Weatherproofing Enclosure	N/A	N/A	2	30.00	60.00
Total Projected Cost						2158.00

FURTHER NOTES

- We have spent about \$1500 (of our original \$2200 budget) so far and have all the necessary parts and supplies...
- We have added a few items:
 - PCB oven
 - Soldering paste dispenser
 - GPS Modules
 - Several thousand SMD components...
- We also need to get the PCB manufactured still, which will be an additional cost. Overall though, we are still well-within budget.
 - Our PCB is ready...
 - We have a manufacturer ready!



STRETCH GOALS

STRETCH GOALS

- Camera (on Gateway)
- External sensors Interface
 - Placement inside the hive is important
 - Weight sensors (load cells)
 - Vibration sensors density to replace load cells + machine learning
 - Additional Sensors
 - Temperature sensor inside hive
 - Humidity
 - Rainfall data
 - Medication + Food sensors + Control System (dispenser)
- Meshing Devices
- GSM Radio
- GPS replaced with GPS-frontend-reciever + Software Defined Radio (\$3 frontend + software versus \$30 module) make the device as inexpensive as possible

DRONES? BECAUSE WHY NOT!!!

- Autonomous drones for land surveying.
- Camera sensors



No one at the party wanted to hear that big and powerful bee *drone* on and on about himself.

THANKS TO OUR SPONSORS



Steven Eisele: Owner

QUESTIONS

IS THIS WHAT ALL THE BUZZ IS ABOUT?!